



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260715000.1	PCN Issued	July 17, 2026
Qualification of RFAB using qualified Process Technology, Design, Datasheet, and BOM options for select devices		Sample request deadline:	September 15, 2026
		Estimated 1st ship date:	October 15, 2026
Sample requests received after September 15, 2026 will not be supported.			

Change type(s)
Assembly Site Assembly Process Assembly Material Packing/Shipping/Labeling Design Data Sheet/Electrical Specification Wafer Fab Site Wafer Fab Material Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the LBC9 qualified process technology, Design, Datasheet, and assembly BOM options for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
SFAB	J11	150mm	RFAB	LBC9	300mm

The die was also changed as a result of the process change.

Construction Differences are as follows:

	Current	Additional
Assembly Site	MLA	Clark-AT
Wire type/diam	Cu; 0.96mil	Cu; 0.80mil
Mount compound	4207768	4225839
Mold compound	4208625	4222198
MSL	Level 2	Level 1

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history shown below. The links to the revised datasheets are available in the table below.



LP2950, LP2951

SLVS582L – APRIL 2006 – REVISED JUNE 2026

	Assembly Site Information			
	Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
	MLA	MLA	MYS	KUALA LUMPUR
	CLARK-AT	QAB	PHL	Angeles City, Pampanga
Sample product shipping label (not actual product label):				
				

Products Affected:			
LP2951-33DRGR	LP2951-50DRGR		

Qualification Report

RedBull LP2951-XXDRG commercial devices| LBC9 in RFAB| package assembled and tested at CLARK A/T
Approve Date 04-June -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LP2951-50DRGR	Qual Device: LP2951-33DRGR	QBS Process Reference: BQ79600PWRQ1	QBS Product Reference: LP2951-50QDRQ1M3	QBS Product Reference: LP2951-50QDRGRQ1M3	QBS Package, Process, Product Reference: LP2951-50QDRGRM3Q1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	1/77/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	1/10/0	3/30/0	3/30/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	1/3/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: LP2951-50DRGR	Qual Device: LP2951-33DRGR	QBS Process Reference: BQ79600PWRQ1	QBS Product Reference: LP2951-50QDRQ1M3	QBS Product Reference: LP2951-50QDRGRQ1M3	QBS Package, Process, Product Reference: LP2951-50QDRGRM3Q1
LU	E4	Latch-Up	Per JESD78	-	-	-	-	1/3/0	1/3/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	3/90/0	1/30/0	-
FTY	E6	Final Test Yield	-	-	1/All/0	1/All/0	-	-	-	1/All/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device LP2951-50DRGR is qualified at MSL1 260C
- Qual Device LP2951-33DRGR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2501-078

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.